

**IN THE SPECIFICATION**

Please amend the specification as follows:

**The paragraph beginning at page 18, line 23 is amended as follows:**

23                   Figure 2C shows one embodiment of a method for fabricating an energy-  
24                   storage device. Steps 251, 253, 259, 261, and 263 are ~~the~~ substantially similar to the  
25                   steps described above with reference to Figure 2B. Step 255C is a step for  
26                   depositing a cathode film at least partially on the cathode contact film. In an  
27                   embodiment, the cathode film is deposited as described above in step 255. In other  
28                   embodiments, the cathode film is deposited according to other deposition processes  
29                   known in the art. The electrolyte film is formed by depositing an electrolyte  
30                   material to a location at least partially in contact with the cathode film (step ~~257B~~ 257C).  
31                   In a preferred embodiment, the electrolyte material is in contact with a substantial

1                   portion of, if not all of, a surface of the cathode film. In some embodiments, an assist  
2                   source simultaneously supplies energized particles to the electrolyte material as it  
3                   forms the electrolyte film. In an embodiment, the assist source supplies a beam of  
4                   energized ions of an assist material different than the electrolyte material. In one  
5                   embodiment, the second material beam is directed to the same location on the  
6                   substrate as the electrolyte material. The energized ion beam assists in controlling  
7                   growth of the structure of the electrolyte film. The ion beam is unfocused in one  
8                   embodiment. The ion beam is ~~focussed~~ focused in another embodiment.

**The paragraph beginning at page 25, line 12, is amended as follows:**

Figure 7 shows another embodiment of a depositing apparatus 705 according to the teachings of the present invention. Depositing apparatus 705 includes a reaction chamber 707 in which is positioned an elongate, flexible substrate 709 on which an energy-storage device is to be fabricated. The substrate 709 is fed from a source roll 710 over an arched thermal control surface 715 and taken up by an end roll ~~713~~ 718. A first material source 711 is provided in the chamber 707 and is a physical deposition source. First source 711 produces a beam of adatoms 712 of a material to be deposited on the substrate 709. In one embodiment, the first source 711 is an arc source including, for example, a cathodic arc source, an anodic arc source, and a CAVAD arc source. In another embodiment, the first source 711 is a physical vapor deposition source including, for example, a sputtering source. In another embodiment, source 711 is a chemical vapor deposition source. Moreover, source 711, in some embodiments, represents a plurality of different material sources. Beam 712 is focused on a location 719 on the substrate 709 whereat the adatoms in the beam are deposited to form a film layer of an energy-storage device. An assist source 713 is provided in the chamber 707 and produces a beam of energized particles 714 directed at the substrate 709. In an embodiment, the assist source 713 produces a beam of energized ions 714. The energized particle beam 714 provides the energy required to control growth and stoichiometry of the deposited material of the first beam 712. Thus, a crystalline structure is formed on the substrate 709 as is explained in greater detail herein. The substrate 709, in one embodiment, is an elastomer, polymer, or plastic web or sheet on which the energy-storage device is fabricated. Substrate 709, being elongate, allows a plurality of energy-storage devices to be deposited on successive locations of the substrate, thereby improving the rate of energy device production. Moreover, a plurality of deposition apparatuses 705 or sources 711, in some embodiments, are provided for simultaneously depositing a plurality of films at different locations on the substrate 709.

**The paragraph beginning at page 26, line 20, is amended as follows:**

20           The above provides descriptions of various embodiments of systems in  
21           which the present invention is performed to produce energy-storage devices or  
22           energy-conversion devices. It is within the scope of the present invention to  
23           combine the elements of the systems in different ways than shown and described as  
24           long as the methods described herein are performable with such a system. For  
25           example, in some embodiments, the flexible substrate 709 and rolls 710, ~~713~~ 718 can be  
26           combined with any of the embodiments shown in Figures 3A-6. In some  
27           embodiments, the thermal source 725 is also combinable with any of the  
28           embodiments of Figures 3A-6. In some embodiments, the pivotable assist sources  
29           413 are combinable with any of the embodiments of Figures 3A, 3B, 5A, 5B, and 7.  
30           In some embodiments, the material sources 511A, 511B, and 511C are combinable  
31           with embodiments of Figures 3A-5A and 6-7.

**The paragraph beginning at page 27, line 1, is amended as follows:**

1           In one embodiment, the electrode second film, e.g., films 59 or 71 is a  
2           lithium-intercalation material which overlays at least part of the first film, e.g.,  
3           contact films 57 or 63, but does not extend beyond the boundary of the first film.  
4           Thus, the intercalation second film remains in a solid state during discharging and  
5           charging of the energy-storage device. In some embodiments, the second film is  
6           deposited using the first deposition source simultaneously with the secondary source  
7           supplying energetic ions to the growing second film. In some embodiments, the  
8           first deposition source is a physical vapor deposition source. In some embodiments,  
9           the secondary source is an ion source supplying energetic ions from a source gas  
10          comprising oxygen (e.g., ~~O<sub>2</sub>~~ O<sub>2</sub>) or nitrogen (e.g., ~~N<sub>2</sub>~~ N<sub>2</sub>). The source gas, in another  
11          embodiment, comprises a noble gas, e.g., argon, xenon, helium, neon, and krypton.  
12          The source gas, in yet another embodiment, comprises a hydrocarbon material such  
13          as a hydrocarbon precursor. Selection of the secondary source gas is based on the  
14          desired effect on the stoichiometry of the deposited film. The secondary source, in  
15          one embodiment, provides a focused beam of energized ions. The secondary  
16          source, in one embodiment, provides an unfocused beam of energized ions. The  
17          energized ions provide energy to the lithium-intercalation material in the range of  
18          about 5 eV to about 3,000 eV. In one embodiment, the energy range of is about  
19          5 eV to about 1,000 eV. The energy range in a further embodiment is about 10 eV  
20          to about 500 eV. The energy range in a further embodiment is about 30 eV to about  
21          300 eV. In another embodiment, the energy range is in the range of about 60 eV to  
22          150 eV. In another embodiment, the energy range is about 140 eV. In an  
23          embodiment, the second film has a thickness of greater than 10 microns. In one  
24          embodiment, the second film has a thickness in the range of about 10 to 20 microns.  
25          In one embodiment, the second film has a thickness in the range of about 1 to 5  
26          microns.

**The paragraph beginning at page 27, line 27, is amended as follows:**

27           An electrolyte third film, e.g., films 61, 61C or 73, having ionic transport  
28           qualities but not being electrically conductive (an electrolyte) is deposited so as to  
29           completely overlay the second deposited film. In one embodiment, the third film is  
30           deposited using a first deposition source and a secondary source supplying energetic  
31           ions to the growing film. In some embodiments, the first deposition source is a

1           physical vapor deposition source. In some embodiments, the secondary source is an  
2           ion source with the capability of supplying energetic ions having an energy greater  
3           than 5 eV. In another embodiment, the energy range is about 5 eV to about  
4           3,000 eV. In one embodiment, the energy range of is about 5 eV to about 1,000 eV.  
5           The energy range in a further embodiment is about 10 eV to about 500 eV. The  
6           energy range in a further embodiment is about 30 eV to about 300 eV. In another  
7           embodiment, the energy range is in the range of about 60 eV to 150 eV. In another  
8           embodiment, the energy of the ions from the secondary source is about 140 eV. In  
9           some embodiments, the secondary source includes oxygen (e.g.,  $O_2$   $O_2$ ) or nitrogen  
10          (e.g.,  $N_2$   $N_2$ ) gas. The secondary source gas, in another embodiment, includes a noble  
11          gas, e.g., argon, xenon, helium, neon, and krypton. The secondary source gas, in  
12          another embodiment, includes a hydrocarbon material such as a hydrocarbon  
13          precursor. Selection of the secondary source gas is based on the desired effect on  
14          the stoichiometry of the deposited film. The secondary source, in one embodiment,  
15          provides a focused beam of energized ions. The secondary source, in one  
16          embodiment, provides a non-focused beam of energized ions. It is desirable to  
17          make the electrolyte, third layer as thin as possible and prevent the cathode and  
18          anode layers from shorting. In an embodiment, the third film has a thickness of less  
19          than 1 micron. In one embodiment, the third film has a thickness in of less than  
20          5,000 Angstroms. In another embodiment, the third film has a thickness of less than  
21          1,000 Angstroms. In another embodiment, the third film has a range of about 10  
22          Angstroms to about 100 Angstroms.

**The paragraph beginning at page 28, line 29, is amended as follows:**

29           An anode, fourth film, e.g., film 65 or 75 includes from a lithium-  
30           intercalation material that is deposited on and overlays the third film but not  
31           contacting first film (barrier) or second film (cathode). In one embodiment, the  
1           fourth film is deposited using a first deposition source simultaneously with a  
2           secondary source supplying energetic ions to the growing fourth film. In some  
3           embodiments, first deposition source is a physical vapor deposition source. In some  
4           embodiments, the secondary source is an ion source supplying energetic ions from a  
5           source gas that includes oxygen (e.g.,  $\text{O}_2$ ) or nitrogen (e.g.,  $\text{N}_2$ ). The source gas, in  
6           another embodiment, includes a noble gas, e.g., argon, xenon, helium, neon, and  
7           krypton. The source gas, in another embodiment, includes a hydrocarbon material  
8           such as a hydrocarbon precursor. Selection of the secondary source gas is based on  
9           the desired effect on the stoichiometry of the deposited film. The secondary source,  
10          in one embodiment, provides a focused beam of energized ions. The secondary  
11          source, in another embodiment, provides an unfocused beam of energized ions. The  
12          energized ions provide energy to the lithium-intercalation material in the range of  
13          about 5 eV to about 3,000 eV. In one embodiment, the energy range of is about 5  
14          eV to about 1,000 eV. The energy range in a further embodiment is about 10 eV to  
15          about 500 eV. The energy range in a further embodiment is about 30 eV to about 100  
16          eV. In another embodiment, the energy range is in the range of about 60 eV to 150  
17          eV. In another embodiment, the energy range of the ions from the secondary source  
18          is about 140 eV. In an embodiment, the fourth film has a thickness of greater than  
19          10 microns. In one embodiment, the fourth film has a thickness in the range of  
20          about 10 to 40 microns.

**The paragraph beginning at page 33, line 6, is amended as follows:**

6           In some embodiments, the materials and compositions of photovoltaic cell  
7           800 are conventional CdS/CdTe materials such as is described in U.S. Patent No.  
8           4,207,119, which is incorporated by reference; with the additional processing  
9           according to the present invention to anneal or treat the surface (e.g., by ion-assist  
10          beam) of the films as they are deposited ~~using~~. In other embodiments, the  
11          compositions used are as described in the following publications, each of which is  
12          incorporated by reference: R.W. Birkmire et al, "Polycrystalline Thin Film Solar  
13          Cells: Present Status and Future Potential," Annu. Rev. Mater. Sci. 1997.27:625-653  
14          (1997); T.L. Chu et al, "13.4% Efficient thin-film CdS/CdTe Solar Cells," J. Appl.  
15          Phys. 70 (12) (15th December 1991); T. Yoshida, "Photovoltaic Properties of  
16          Screen-Printed CdTe/CdS Solar Cells on Indium-Tin-Oxide Coated Glass  
17          Substrates," J. Electrochem. Soc., Vol. 142, No. 9, (September 1995); T. Aramoto  
18          et al., "16% Efficient Thin-Film CdS/CdTe Solar Cells," Jpn. J. Appl. Phys. Vol. 36  
19          pp 6304-6305 (Oct. 1997); R.B. King, ed. "Encyclopedia of Inorganic Chemistry"  
20          Vol 3., pp 1556-1602, John Wiley & Sons Ltd., (1994).

**The paragraph beginning at page 33, line 26, is amended as follows:**

26           In a heterojunction photovoltaic cell, the semiconductor films are formed of  
27           different materials. For a rectifying junction, the semiconductor films must also be  
28           of different type, that is p or n type. The junction between the two semiconductor  
29           films is both a pn junction and a heterojunction. The first semiconductor film on  
30           which solar light is incident has a band gap higher than that of the second  
31           semiconductor film. The band gap of a semiconductor is the energy separation

1           between the semiconductor valance band and the conduction band. The band gap of  
2           this first semiconductor film is chosen so that it corresponds to light in the short  
3           wavelength region of the solar spectrum. Photons of light having energy equal to or  
4           greater than the band gap of the first semiconductor film are strongly absorbed, but  
5           photons of light of energy less than the band gap of the first semiconductor pass  
6           through the first semiconductor and enter the second semiconductor film. Examples  
7           of materials used for the first semiconductor film include CdS, ZnS, CdZnS, CdO,  
8           ZnO, CdZnO, or other wide band gap semiconductors like SiC, GaN, InGaN, and  
9           AlGaN. The second semiconductor film is chosen from materials that have band  
10          gaps that correspond well to the long wavelength onset of solar radiation. Materials  
11          such as CdTe, ~~CuInSe<sub>2</sub>~~ CuInSe<sub>2</sub>, InP, GaAs, InGaAs, InGaP, and Si are examples of  
12          materials for the second semiconductor film.



**The paragraph beginning at page 52, line 30, is amended as follows:**

30                   Figure 15H shows that the batteries have been folded along the fold lines to  
31                   form a stack of three batteries ~~1100~~, 1110, 1110' and 1110". The folds shown in

1                   Figure 15H are a fan fold. Once the fan fold is formed, as shown in Figure 15H, the  
2                   fan folded battery, including three cells 1330, can be formed in any desired shape,  
3                   such as ~~these shown in~~ square-sided shape 1503 of Figure 15C, angle-sided shape  
                      1504 of 15D and curve-sided shape 1505 of 15E. The three-celled or multi-celled  
4                   unit 1330 can be adhered to the interior or exterior surface of any electronic device,  
5                   as discussed above. It should be noted that the fan fold can include more than three  
6                   batteries or less than three batteries. The inventive aspect is that it includes a  
7                   plurality of batteries. The cells 1110, 1110' and 1110" can be attached to one  
8                   another so that the cells are in series after they are diced. Another possibility is that  
9                   the electrical contacts for each of these could be put in contact with one another as a  
10                  result of fan folding the multi-celled unit 1330.

**The paragraph beginning at page 53, line 11, is amended as follows:**

11           Figures 15I, 15J and 15K show yet another embodiment of the invention. In  
12           this particular embodiment of the invention, the sheet of electrical cells 1300  
13           includes a plurality of cells including 1110 and 1110'. The entire sheet 1300 is then  
14           vacuum formed to form more or less an egg carton 1350 with individual battery  
15           cells 1110 and 1110' being formed within well 1360 and 1362 in the sheet 1300.  
16           Between the wells 1360 and 1362 is a living hinge 1370. The batteries 1110 and  
17           1110' are at the bottom of each well ~~1160 and 1162~~ 1360 and 1362, as shown in Figure 15K. The  
18           living hinge 1370 is positioned between the two wells 1360 and 1362. The first cell  
19           1360 can be folded on top of the second well 1362 to form an electronic device  
20           enclosure 1380, as shown in Figure 15L. It should be noted that the size of the  
21           battery portions 1110 and 1110' can be limited or placed so that other traces and  
22           room for other electronic devices can be added so that a total circuit can be formed  
23           within a disc enclosure. This provides for an advantage that wherein the electronic  
24           component could be directly placed into the wells 1160 and 1162 at sites formed at  
25           the same time as the batteries were deposited onto the sheet 1300. After placing all  
26           the various electronics, the electronic device can be formed merely by dicing two of  
27           the wells 1360 and 1362 so that they form a top and bottom of the device enclosure  
28           1380. All sorts of electronic devices could be included, including an LCD or other  
29           display device. The LCD may be readable directly through a sheet if it is  
30           transparent or the sheet, or one of the wells 1360 and 1362, may be provided with an  
31           opening that would correspond to an opening or face of the display of an LCD or

1           other display device. Thus, the sheet and the deposited battery thereon can  
2           ultimately become the exterior surface or the enclosure for the device formed on the  
3           sheet. This has a great advantage in that the process steps necessary to form a  
4           device are or can be quite easily and efficiently done in a continuous process. This  
5           would lead to very efficient manufacturing of electronic devices.

**The paragraph beginning at page 54, line 6, is amended as follows:**

6           Figure 16A is a plan view of a sheet including a plurality of cells 1110  
7           according to this invention. Figure 16A, 16B and 16C show a way to form a  
8           laminated battery cell and possibly laminated battery cell and electronics for a smart  
9           card or other invention that includes a battery and electronics within a card. The  
10          sheet 1300 shown in Figure 16A includes cells 1110. The sheet also includes fold  
11          lines 1390 and 1392. The sheet 1300 is diced into individual sections, which  
12          include fold lines 1390 and 1392, as well as a battery cell site 1110. The battery cell  
13          site might also include electronics that are also deposited with the battery or energy  
14          source onto the sheet 1300. The diced portion 1400 includes one portion including  
15          the cell 1100 and two blank portions 1402 and 1403. The diced portion 1400 is then  
16          fan folded, as shown in Figure 16C. Once a fan fold has been formed, the cell  
17          portion 1110 is captured between the two unpopulated sheet portions 1402 and 1403  
18          and will provide an extra protective layer. The excess portions of the sheet 1300  
19          can be trimmed, as shown in Figure 16D to produce a smart card or card including  
20          both a battery 1110 and electronic, as shown as item 1600E in Figure 16E.

**The paragraph beginning at page 54, line 21, is amended as follows:**

21           Figure 17 is an exploded perspective view of a diced portion of a sheet 1300  
22           which includes one battery cell 1110 rolled around an electrical motor 1500. In this  
23           case, the diced portion ~~1300~~, which includes a cell 1110, is an elongated strip 1510  
24           from the original sheet 1300. The elongated strip 1510 may include several  
25           batteries placed in series or one elongated battery that is laid down as a strip on the  
26           sheet 1300. The electrical motor is electrically connected to the anode and cathode  
27           of the battery and then rolled on to the electrical motor 1500. In this case, the strip  
28           1510, on which the battery has been deposited, becomes the case for the electrical  
29           motor or also can be viewed as being a part of the case of the electrical motor. The  
30           electrical motor can be provided with a sprocket 1520 that is used to drive another  
31           gear 1530 having a shaft 1532 attached thereto. As shown in Figure 17, a chuck

1           1540 is placed upon the shaft 1532 to form a drill or other power tool.  
2           Advantageously, the power tool could be light and compact, as well as being  
3           capable of being recharged a multiplicity of times. The power tool could be a  
4           hand held drill for homeowner use or a smaller device, such as a Dremel-brand  
5           rotary hand tool.

**The paragraph beginning at page 55, line 21, is amended as follows:**

21           Figures 18C and 18D show another embodiment of the invention for a  
22           lighting device. In this particular embodiment, again a strip 1600 is provided with a  
23           switch 1602 and an LED 1604. In this particular embodiment, the LED is  
24           positioned so that it extends beyond the length of the sheet 1600. In this particular  
25           embodiment, the sheet 1600 is rolled along its longer dimension around the LED  
26           1604 to form an elongated case having the LED 1604 at one end of the case and a  
27           switch 1602 at the other end of the case. This forms a light emitting diode light  
28           1630 in which the ~~dice~~ sheet 1600 is part of the case.

**The paragraph beginning at page 57, line 12, is amended as follows:**

12           A second process is shown in Figure 21B. The second process shown in  
13           Figure ~~19B~~ 21B is useful for devices in which the battery 1110 may be removed easily  
14           from the enclosure portion. As before, the first step, depicted by reference numeral  
15           1930, is to determine if the electronics are obsolete. If they are, the battery 1110 is  
16           merely removed from the case for the enclosure portion and recycled for use in  
17           another enclosure portion having a similar contour, as depicted by reference  
18           numeral 1950.

**The paragraph beginning at page 60, line 21, is amended as follows:**

21           Figure 22G shows a block diagram perspective view of an integrated device  
22           ~~2207~~ 2203 implementing circuit 2200 of Figure 22A having the battery 2320 and the  
23           circuit 2330 built side-by-side on a substrate 2310. In some embodiments, a pattern  
24           of conductive areas or traces is deposited on substrate 2310, and the successive  
25           layer(s) of battery 2320 and circuit 2330 are then deposited. In some embodiments,  
26           circuit 2330 consists only of these conductive traces. In other embodiments, one or  
27           more of the process steps or deposited layers of battery 2320 and circuit 2330 are  
28           common, and thus performed at substantially the same time for both circuit 2330  
29           and battery 2320, thus increasing the reliability, speed and yield of fabrication and  
30           lowering the cost of fabrication. In the embodiment shown, trace 2318 is deposited  
31           on substrate 2310 and forms a common bottom electrical connection for both circuit  
1           2330 and battery 2320. Other aspects of Figure 22G can be understood by  
2           reference to Figures 22A-22C.

**The paragraph beginning at page 62, line 11, is amended as follows:**

11           Figure 24A shows a perspective view of an embodiment 2400 of the present  
12 invention having a battery 2320 overlaid with an integrated device 2430. In some  
13 embodiments, integrated device ~~2340~~ 2430 is a so-called supercapacitor relying on either  
14 charge accumulation on opposing sides on an insulator (as in a capacitor) or ion  
15 transport across an electrolyte (as in a battery), or both charge accumulation and ion  
16 transport to store electrical energy. In some embodiments, integrated device ~~2340~~ 2430  
17 includes a photovoltaic cell of conventional construction deposited directly on  
18 battery 2320.

**The paragraph beginning at page 62, line 19, is amended as follows:**

19           Some embodiments further include a separately fabricated circuit device  
20 such as an integrated circuit chip 2440 that is wire-lead bonded to device 2430 using  
21 wire 2441, to device-battery common terminal 2324 using wire 2443, and to bottom  
22 battery contact 2322 using wire 2442. For example, in one embodiment having a  
23 supercapacitor device 2430, integrated circuit ~~2430~~ 2440 includes a wireless  
24 communication circuit that uses the battery for overall power needs and uses  
25 supercapacitor device 2430 for quick-burst power needs such as for transmitting  
26 short burst of data to an antenna. Other embodiments include other fabricated  
27 circuit devices such as switches, LEDs or other light sources, LCD displays,  
28 antennas, sensors, capacitors, resistors, etc., wired to device 2400.

**The paragraph beginning at page 67, line 23, is amended as follows:**

23           Figures 25B-25E show a fabrication sequence for cofabrication of solid-state  
24           integrated circuits and solid-state energy source such as that described above, but  
25           onto a packaged IC 2540. Figure 25B shows a plan view and Figure 25C shows an  
26           elevational view of IC 2540. In some embodiments, IC 2540 includes a silicon chip  
27           2545 having integrated components such as transistors, resistors, memory, etc., a  
28           lower substrate ~~2540~~ 2546, and a wiring superstrate 2544 having deposited wires ~~2540~~ 2543  
29           that extend to bonding vias 2542. Figure 25D shows a plan view and Figure 25E  
30           shows an elevational view of an integrated battery-IC 2501. Battery-IC 2501  
31           includes a cathode 2326 (e.g., lithium cobalt oxide), electrolyte layer 2327 (e.g.,

1           LiPON), and anode layer 2328 (e.g., including copper, carbon, lithium, lithium-  
2           magnesium, and/or other suitable anode material). Passivation overcoat layer 2329  
3           suitable to protect the inner components of battery 2320 is then deposited or grown.

**The paragraph beginning at page 68, line 4, is amended as follows:**

4           In one embodiment, the ~~product~~ packaged IC 2540 ~~product~~ is formed by conventional  
5           means. All machine work and cleaning is accomplished. The package 2540 is sent  
6           to energy processing for deposition of battery 2320 or other energy-storage device.  
7           The design of the package included a suitable area 2549 for deposition of battery  
8           components. Using shadow masks with sufficient overlay accuracy, the necessary  
9           components of the energy structure (e.g., a battery and/or photovoltaic cell) are  
10          deposited using the methods described above. A final passivation coating 2329 is  
11          applied to the energy stack structure. The package with energy structure integrated  
12          is sent for assembly.

**The paragraph beginning at page 69, line 1, is amended as follows:**

1           Figure 25F shows a block diagram of a layer-deposition system 2560 much  
2           the same as that of Figure 24B, however rather than using a sheet of polymer or  
3           other homogenous substrate material 2410, system 2560 starts with a sheet 2561  
4           having a plurality of processed circuits packaged ICs 2540 that are received by takeup reel 2563.

**The paragraph beginning at page 69, line 9, is amended as follows:**

4           Figure 26A shows a perspective view of an device 2600 of the present  
5           invention having an integrated circuit 2510 overlaid on its back with a battery 2320.  
6           This embodiment is similar to that of Figure 25A, except that the battery 2320 is  
7           deposited on the back of IC 2510, and is wire-lead bonded to contact 2514 using  
8           wire 2614 from battery contact 2519 and to contact 2515 using wire 2615 from battery contact 2518.

**The paragraph beginning at page 70, line 5, is amended as follows:**

5           In some embodiments, embodiment 2600 further includes an antenna or  
6           electromagnetic radiation receiving loop ~~2660~~ 2662 fabricated on a surface of integrated  
7           circuit 2510, for example, on the opposite side as that facing battery 2320. In some  
8           such embodiments, device 2600 also includes one or more devices 2650 such as  
9           sound transducers for such applications as a hearing aid having an combined  
10          transducer-battery-amplifier device in order to provide a radio frequency-wave-  
11          rechargeable hearing aid which could be taken out of the ear at night and placed in an  
12          RF-emitting recharging stand (e.g., that of Figure 27M), avoiding the need to  
13          replace batteries or even to electrically connect to an external recharging circuit.



**The paragraph beginning at page 70, line 14, is amended as follows:**

14           In various embodiments, such an antenna or electromagnetic radiation  
15       receiving loop ~~2660~~ 2662 is fabricated on device 2202, 2203, ~~2203~~, 2204, 2206, 2207,  
16       2208, 2300, 2400, or 2500 (or 2700 described below) or other battery devices  
17       described herein. In some such embodiments, electromagnetic radiation received  
18       wirelessly by antenna ~~2660~~ 2662 can be such low-frequency radiation as 50- or 60-hertz  
19       magnetic radiation from a coil connected to house current (e.g., that of Figure 27L).  
20       In other such embodiments, RF radiation such as radio, TV, cellular, etc. having  
21       frequencies up to and exceeding 2.4 GHz is received. In some embodiments,  
22       multiple antennae are used, e.g., one for transducing communications signals and  
23       another for receiving recharging signals.

**The paragraph beginning at page 73, line 6, is amended as follows:**

6           Figure 27L shows an perspective view of a device 2700 of Figure 27E, but  
7       further including a photovoltaic cell 2650, at a light-recharging station that includes  
8       lamp 2791. In some embodiments, device 2700 is fabricated in a shape to fit in the ear,  
9       includes sound transducers, and functions as a hearing aid that can be recharged an  
10      indefinite number of times, eliminating the need to replace its battery.

**The paragraph beginning at page 73, line 16, is amended as follows:**

16           Solid-state rechargeable batteries such as those described above have the  
17           unique ability of being integrated directly with the electronics they will power.  
18           Further integration of thin-wire antenna/coil ~~2660~~ 2662 or 2750 to be used as one of the  
19           coils of a two-part transformer such as shown in Figure 27K and/or RF-scavenging  
20           technology such as that used in keyless entry systems allows the recharging of the  
21           solid-state thin-film battery 2320 wirelessly (through the air). Using techniques  
22           already common in RF I.D. tagging, the communicated energy is converted into a  
23           D.C. voltage and used to perform functions on board. In the case where a battery  
24           already exists on board, the D.C. voltage is used to power up recharge circuitry to  
25           wirelessly recharge the on-board battery.

**The paragraph beginning at page 74, line 29, is amended as follows:**

29           Figure 31C shows one method for making a pacemaker 3102. The method  
30           includes a plurality of steps carrying the reference numbers 3194, 3195, 3196 and  
31           3197. The pacemaker 3102 includes a first half 3131 and a second half 3130. In the  
1           initial step, 3194, the second half 3130 is provided. A battery cell 1110 is formed  
2           on an interior surface of the pacemaker 3102, as shown by step 3195. The single  
3           cell 1110 is deposited on the interior surface, as shown by step 3195. ~~as shown in~~  
4           ~~step 3194~~. The electronics 3150 are then placed onto the battery 1110 to form a  
5           circuit with the battery 1110, as depicted by step 3196. The first half 3131 of the  
6           enclosure is placed over the second half 3130 to form the assembled pacemaker  
7           3102, as depicted by step 3197.

**The paragraph beginning at page 76, line 23, is amended as follows:**

23           Of the 2 billion rechargeable batteries consumed in the United States in  
24           1998, only about 300 million were actually recycled. That means about 1.7 billion  
25           recyclable batteries made it into landfills. Although more and more of these  
26           batteries are technically environmentally safe, this still represents a significant load  
27           on the landfill situation in the USA. The present invention provides a solution that  
28           will have its greatest impact as solid-state lithium-ion batteries begin to dominate  
29           the rechargeable battery market. In this invention, solid-state lithium-ion batteries  
30           have a date code and/or recycle value associated with them. Because of the very  
31           large (over 40,000) number of charge/discharge cycles possible with solid-state

1           lithium batteries, the average expected life of a cell could exceed 100 years. It is  
2           therefore very likely that the product in which the cell is placed will lose its  
3           usefulness well before the battery cell is depleted. Thus, when the battery reaches  
4           the end of its useful life based on the obsolescence of the product it was in, the  
5           consumer will be enticed to recycle the battery based on the value returned to the  
6           consumer in exchange for recycling. This value could be a function of the date code  
7           and application the battery was used in. The recycler 2810 then disassembles the  
8           unit 2800, tests the single cells 2801, and then rebuilds the cells in whatever  
9           configuration is most in demand at that time. The rebuilt unit ~~2800~~ could then be  
10          sold at an appropriate cost and warranty on performance.

**The paragraph beginning at page 78, line 27, is amended as follows:**

27           Figure 29A shows a block diagram of a layer-deposition system 2960.  
28           System 2960 has layer deposition sections 2962 much the same as those of ~~Figure system~~  
29           2460 of Figure 24B, except that it is set up to deposit layers onto wafers 2961 (or  
30           onto diced ICs 2510 rather than onto flexible substrates), resulting in processed  
31           wafers 2963. Figure 29B shows a  
1           perspective view of a partially processed wafer 2964 having battery material 2320  
2           on wafer 2961 or IC 2410.

**The paragraph beginning at page 79, line 3, is amended as follows:**

3           Figure 29C shows a block diagram of a layer-deposition system 2965.  
4           System 2965 has layer deposition sections 2962 much the same as those of ~~Figure system~~  
5           2465 of Figure 24D, except that it is set up to deposit layers onto wafers ~~2961~~ 2966 (or  
6           onto diced ICs 2510 rather than onto flexible substrates) by layer-deposition sections  
             2967, resulting in processed wafers 2968. Figure 29D shows a  
7           perspective view of a processed sheet 2969 having battery material 2320 on wafer  
8           2961 or IC 2410 and covered by a device 2430 such as a photovoltaic cell.

**The paragraph beginning at page 79, line 9, is amended as follows:**

9           Figure 29E shows a block diagram of a layer-deposition system 2965. In  
10 some such embodiments, system 2965 deposits layers forming a photovoltaic cell  
11 device 2650 onto a wafer 2971 or IC 2510. Figure 29F shows a perspective view of  
12 a partially processed wafer 2974. Figure 29G shows a block diagram of a layer-  
13 deposition system 2960. In some such embodiments, system 2960 deposits layers of  
14 a battery 2320. Figure 29H shows a perspective view of a processed wafer 2979. In  
15 some embodiments, wafer 2979 represents a single device, and in other  
16 embodiments, wafer 2979 is diced or cut into a plurality of individual devices and  
17 then wired as necessary to connect the signals on the top of the device to the bottom  
18 of the device. Figure 29I shows a perspective view of wired diced final device  
19 2600 having wires 2914 and 2915.

**The paragraph beginning at page 80, line 15, is amended as follows:**

15           Figure 31B shows the method for making the pacemaker ~~3100~~ 3101. The method  
16 is comprised of a plurality of steps carrying the reference numbers 3190, 3191, 3192  
17 and 3193. The pacemaker 3100 includes a first half 3131 and a second half 3130. A  
18 plurality of battery cells 1110 are formed on a substrate material 3140, as shown by  
19 step 3190. The substrate material 3140 is diced or cut resulting in a single cell 1110  
20 on the sheet as diced. The single cell 1110 is adhesively bonded to the second half  
21 3130 of the pacemaker 3100, as shown in step 3191. The electronics 3150 are then  
22 placed onto the battery 1110 to form a circuit with the battery 1110, as depicted by  
23 step 3192. The first half 3131 of the enclosure is placed over the second half 3130  
24 to form the assembled pacemaker 3100.